

Low-Profile, Shielded Drum Core, Tapped Inductor

SDT30 Series



Description

- Halogen Free
- Approved for use with Maxim® MAX14521 chip set
- 125°C maximum total temperature operation
- 3.1 x 3.1 x 1.0mm shielded drum core
- · Ferrite core material
- Low losses
- High efficiency
- · Reduces peak output currents
- · Magnetically shielded, low EMI
- RoHS compliant

Applications

- Keypads
- Instrument clusters
- EL backlighting
- Buck or boost inductor

Environmental Data

- Storage temperature range: -40°C to +125°C
- Operating temperature range: -40°C to +125°C (with derated current)
- Solder reflow temperature: J-STD-020D compliant

Packaging

- Supplied in tape-and-reel packaging, 5000 parts per reel, 13" diameter reel
- Also supplied in tape-and-reel packaging, 7" diameter reel. See product specifications table note 5 below.



Product Specifications								
Part	Pin	OCL ¹	Part Marking	Turns Raito	I _{rms} ²	I _{sat} ³	DCR (m Ω)	
Number⁵	Numbers	(μH)	Designator	Primary:Secondary	(Amps)	(Amps) @25°C	@20°C	K-factor⁴
SDT30-127-R	(1 - 2) Primary	2.9 ± 30%	_	1.7	0.60	0.85	0.41 ± 15%	856.0
SD130-121-K	(2 - 3) Secondary	148 ± 20%	A	1:7	0.13	0.12	9.0 ± 15%	N/A

- 1 Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.10V_{rms}, 0.0Adc
- 2 I_{rms} : DC current for an approximate temperature rise of 40°C without core loss when either the primary or secondary winding is running separately. Derating is necessary for AC currents. PCB pad layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended the part temperature not exceed 125°C under worst case operating conditions verified in the end application.
- 3 I_{sat}: Peak current for approximately 30% rolloff at +25°C of primary or secondary with another winding open.
- 4 K-factor: Used to determine B_{p-p} for core loss (see graph). $B_{p-p} = K \star L \star \Delta I$. B_{p-p} : (Gauss), K: (K-factor from table), L: (primary inductance in μ H), Δ I (peak-to-peak ripple current in amps).
- 5 Part Number Definition: SDT30-x2x-yy-R
- SDT30 = Product code and size
- -x2x = Turns ratio (first "x" = primary winding, "2" = ":" and second "x" = secondary winding) e.g., -127 = 1:7 primary to secondary turns ratio.
- -yy = add "T7" for 7 inch tape-and-reel package. Leave blank for 5000 parts on 13 inch tane-and-reel package.

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• "-R" suffix = RoHS compliant

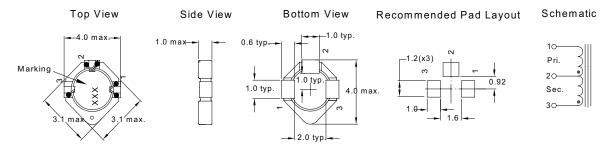
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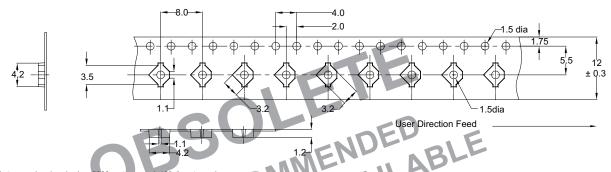


Dimensions - mm



Part Marking: Three digit marking; 1 digit indicated inductance value per Part Marking Designator chart, 2 digit indicated bi-weekly production date code, 3 digit is last digit of the year produced.

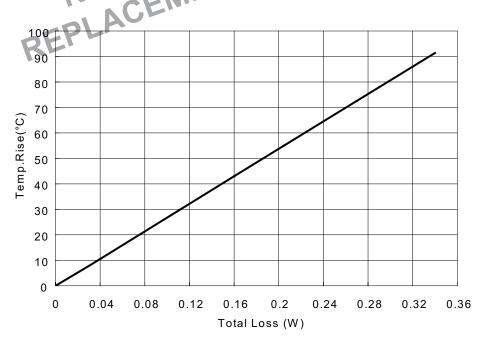
Packaging Information - mm



Supplied in tape-and-reel packaging, 5000 parts per reel, 13" diameter reel.

Also supplied in tape-and-reel packaging on 7" diameter reel (not shown above). See product specifications table note 5 on page 1 for ordering deta

Temperature Rise vs.Total Loss

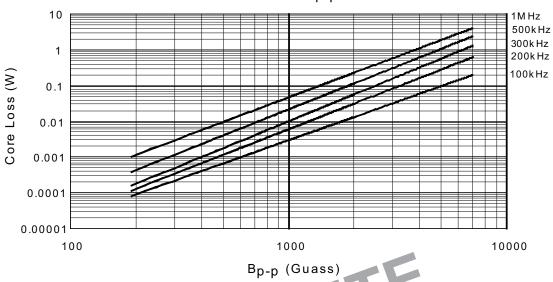


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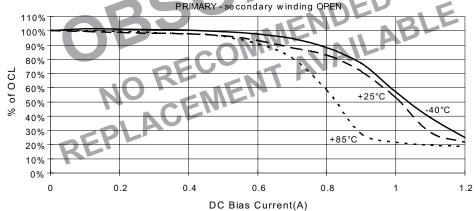
Core Loss

Core Loss vs. B_{p-p}

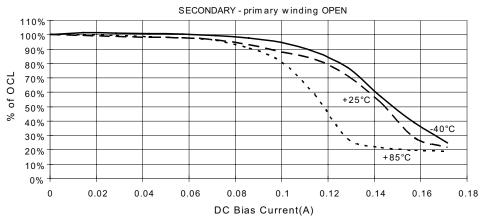




% of OCL vs. DC Bias current PRIMARY-secondary winding OPEN



% of OCL vs. DC Bias current



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Solder Reflow Profile

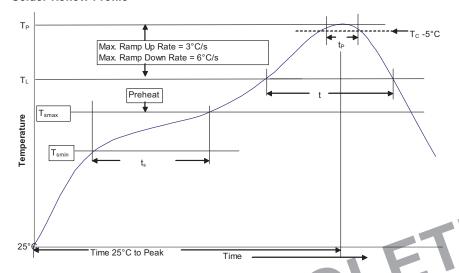


Table 1 - Standard SnPb Solder (T_C)

	Volume	Volume
Package	mm³	mm³
Thickness	<350	≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (Tc)

	Volume	Volume	Volume
Package	mm³	mm³	mm³
Thickness	<350	350 - 2000	>2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder			
Preheat and Soak • Temperature min. (T _{smin})	100°C	150°C			
 Temperature max. (T_{smax}) 	150°C	200°C			
• Time (T _{smin} to T _{smax}) (t _s)	60-120 Seconds	60-120 Seconds			
Average ramp up rate T _{Smax} to T _p	3°C/ Second Max.	3°C/ Second Max.			
Liquidous temperature (TL)	183°C	217°C			
Time at liquidous (t _L)	60-150 Seconds	60-150 Seconds			
Peak package body temperature (T _P)*	Table 1	Table 2			
Time $(t_p)^{**}$ within 5 °C of the specified classification temperature (T_c)	20 Seconds**	30 Seconds**			
Average ramp-down rate (T _p to T _{smax})	6°C/ Second Max.	6°C/ Second Max.			
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.			

 $^{^{\}star}$ Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

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^{**} Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.